



















STATICO | ESD VINYL TILE |



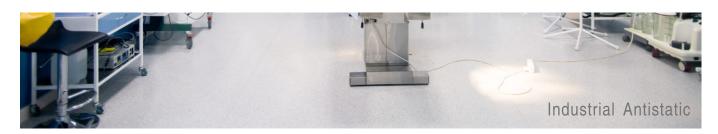


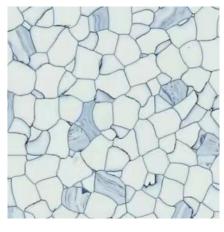


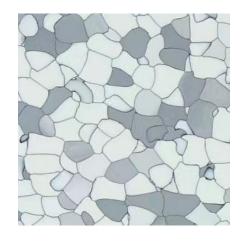










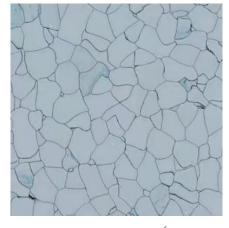




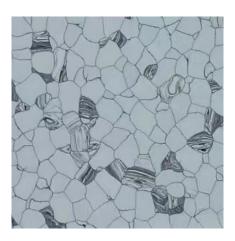
HP-ESD-501 ≠

HP-ESD-502 ≠

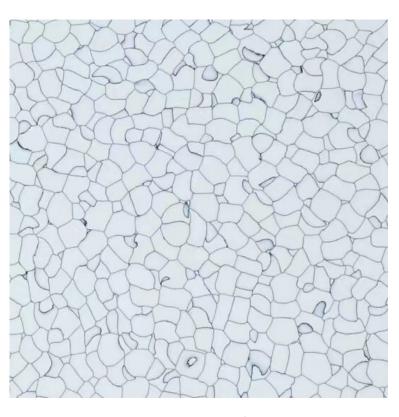
HP-ESD-503 ≠



HP-ESD-504 €



HP-ESD-505 ≠

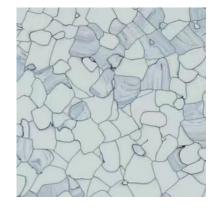


HP-ESD-506 €

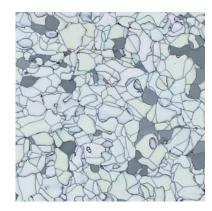
### Copper Foil







HP-ESD-507 ≠



HP-ESD-508 ≠



HP-ESD-509 ≠



HP-ESD-510 ≠



HP-ESD-511 ≠



HP-ESD-512 ≠

## **PVC Welding Rod**

H/019	
H/016	
H/018	
H/005	
H/031	
H/037	





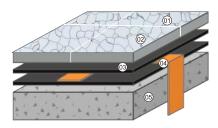


# **ESD Control Vinyl Tile**



### Electrostatic Hazard

In today's technological environment, static electricity is no longer just a troublesome simple shock wave, static electricity radiation will not only damage and degrade the sensitivity of electronic components, but also ignite flammable gases, triggering great safety hazards and electronic equipment failure, thus causing heavy economic losses. So how to dissipate static electricity is the most important problem, Hedsom anti-static flooring has the optimal solution to the above static electricity problems.



- 01 PVC Welding Rod
- 02 PVC ESD Vinyl Tile Floor
- 03 Conductive Adhesive
- 04 Laying Copper Foil
- 05 Original Based Floor

### **Features**

- 1. Durable, practical, and economical covering especially for ESD building application
- 2. Consistent static conductive performance throughout the space
- 3. Excellent chemical, abrasion, and puncture resistance
- 4. No waxing required, great life cycle value
- 5.According to ASTM F150-98 (Standard test method for electrical resistance of conductive and static dissipative resilient flooring)
- 3.11 Conductive flooring tile:  $2.53 \times 10^4 \Omega \sim 1.03 \times 10^6 \Omega$ . Most applications in the cleaning room, lab or factory ESD discharge area will use the conductive floor tile.
- 3.12 Dissipative flooring tile:  $1.03 \times 10^6 \Omega \sim 1.03 \times 10^9 \Omega$ . Most applications in the data center and facility room will use the dissipative tile.

ESD Control Vinyl Tile has been widely applied to e-shop, clean rooms, communication rooms and other precision instruments and rooms for equipment operation.



Laboratory



Electronic Factory



Numerical Control Room



Medical Clean Room



R&D Center

### 01.Self Leveling Compound (After Primer application)

The site condition to paving the tiles need good leveling basic floor. Self leveling is applied before installation.



Conductive adhesive should be used after self leveling. The tiles will be glued. The heavy roller should be running after gluing to make the stick stronger.

#### 03.Copper Foil

Copper foil will form a 600mm by 600mm cross network. It will be glued by conductive adhesive or self glued. Copper foiled should be underlaid the tiles, not in the joints area.

#### 04. Welding Rod

Welding rod will be used in the joints of tiles for make all the tiles to form an integral surface covering.

#### **05.Conductivity Test**

The copper foil should be connected to the earthing system of the building. Then the electrical resistance can be test by equipment after cleaning work.

#### 06.Maintenance

Avoid sharps scratch on the floor surface, cleaning the floor by neutral products. Spots or unremovable dirty should be clean by cleaning machine. Anti static wax should be applied on the surface after cleaning for better durability.























## **Technical Data**

	ITEM	STANDARD	INDEX
	SIZE	SJ/T11236-2020 ISO 24342{EN427}	600*600mm 610*610mm
	THICKNESS	SJ/T11236-2020 ISO 24346{EN428}	2.0/3.0mm
4	ELECTRICAL RESISTANCE(Ω)	SJ/T11236-2020 EN 1081	1.0*10 <sup>4</sup> -1.0*10 <sup>6</sup> 1.0*10 <sup>6</sup> -1.0*10 <sup>9</sup> 10 <sup>5</sup> -10 <sup>9</sup>
	BOBY VOLTAGE	IEC 61340-4-5  ANSI ESD STM97.2  EN 1815	<100V <100V <2KT
		GJB3007A-2009	≤2(Sec)
	STATIC DECAY	Federal Test Method 1018 Method 4046	0.01sec 0.01sec
	(1000r)	SJ/T11236-2020	≤0.02g/cm²
	RESISTANCE TO WEAR	EN660-2	Р
	FIRE RESISTANCE	SJ/T11236-2020 GB8624-2012 ASTM E648-17 EN13501-1	FV-0 B <sub>1</sub> {B-S1,t0} Class I B <sub>tt</sub> -S1
	DIMENSIONAL	ASTM F2199:09(2014) IOS 23999	≤0.25%
Kis	SLIP RESISTANCE WET	DIN 51130	R9
	RESIDUAL CONCAVITY	GB/T4085-2015 EN ISO 24343-1	0.15<1 <sub>R</sub> ≤0.40mm ≤0.10mm
->0-	COLOR FASTNESS	ISO 105-B02	≥6
<u> </u>	CHEMICAL PRODUCTS RESISTANCE	EN ISO 26987	ok
٠٠٠	TOXIC TESING	GB 18586-2001 EN 71-3	ok
	TVOC After 28 Days	ISO 16000-6	<10µg/m³